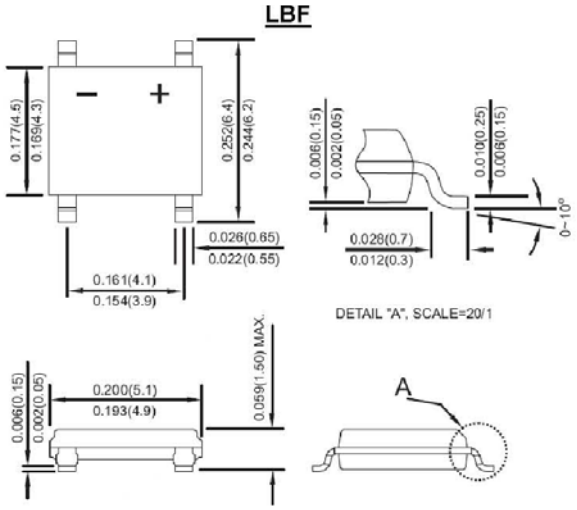
TB1S~TB10S

Surface Mount Flat Bridge Rectifier

Reverse Voltage - 100 to 1000 V
Forward Current - 0.8 A



Dimensions in inches and (millimeters)

Features

- Ideal for printed circuit board
- Glass passivated chip
- Reliable low cost construction utilizing molded plastic technique
- Small size, simple installation

Mechanical Data

- **Terminal**: Plated leads solderable per MIL-STD 202E, method 208C
- **Case**: UL-94 Class V-0 recognized flame retardant epoxy
- **Polarity**: Polarity symbol marked on body

Maximum Ratings and Electrical characteristics

Single-phase, half-wave, 60 Hz, resistive or inductive load rating at 25 °C, unless otherwise stated, for capacitive load, derate current by 20 %.

Parameter	Symbols	TB1S	TB2S	TB4S	TB6S	TB8S	TB10S	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current on Glass-expoxy P.C.B.	$I_{F(AV)}$	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25						A
Maximum Instantaneous Forward Voltage at Forward Current 0.4 A	V_F	0.95						V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a = 125 °C	I_R	5 100						μA
Typical Thermal Resistance Junction to Lead On Glass-expoxy P.C.B.	$R_{\theta JL}$ $R_{\theta JA}$	42 88						°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150						°C

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

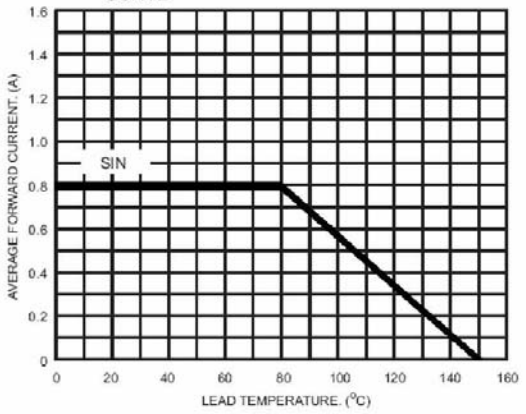


FIG.2- TYPICAL FORWARD CHARACTERISTICS

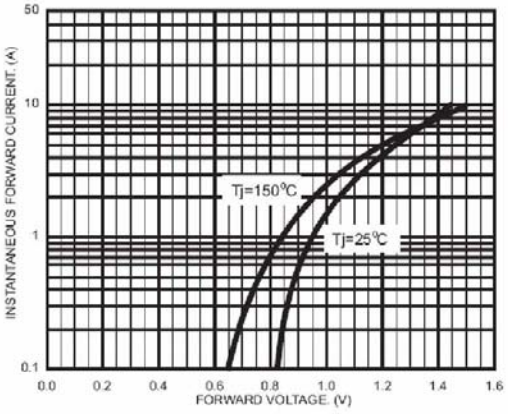


FIG.3- MAXIMUM FORWARD CURRENT DERATING CURVE

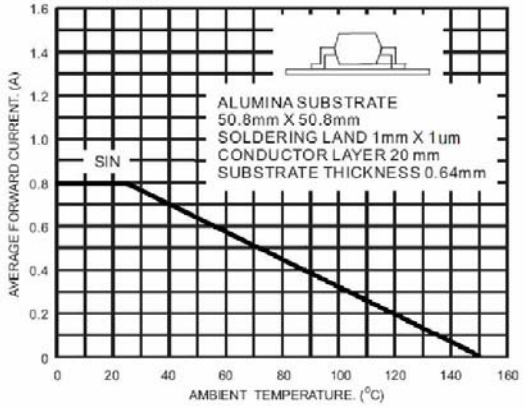


FIG.4- FORWARD POWER DISSIPATION

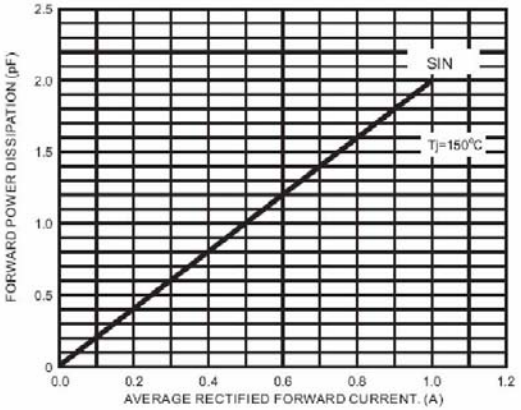


FIG.5- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT